



materials



an Open Access Journal by MDPI

Modeling, Simulation and Data Processing for Additive Manufacturing

Guest Editor:

Dr. Mika Salmi

Department of Mechanical Engineering, Aalto University, 02150 Espoo, Finland

Deadline for manuscript submissions:

closed (30 June 2021)

Message from the Guest Editor

Dear Colleagues,

Businesses based around additive manufacturing have experienced double-digit growth in recent years. Accordingly, we have witnessed huge efforts in material and equipment development, which have opened up new application possibilities not previously in existence. However, it can be seen that increasingly more development efforts are needed, not only in addressing hardware but also concerning the modeling of materials and designs, topology optimization, process simulation and optimization, data processing, and total process flow for AM parts.

The objective of this Special Issue is to provide a forum for researchers and practitioners to exchange their latest achievements and to identify critical issues and challenges for future investigations on “Modeling, Simulation and Data Processing for Additive Manufacturing”.

Dr. Mika Salmi
Guest Editor



mdpi.com/si/36316

Special Issue



an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.

Journal Rank: JCR - Q1 (Metallurgy and Metallurgical Engineering) / CiteScore - Q2 (*Condensed Matter Physics*)

Contact Us

Materials Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/materials
materials@mdpi.com
[X@Materials_Mdpi](https://twitter.com/Materials_Mdpi)